PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hong Hocheng	10/23/2008
Chin Chung Nien	10/21/2008

RECEIVING PARTY DATA

Name:	National Tsing Hua University	
Street Address:	101 Section 2, Kuang-Fu Road	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	30013	

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	6909998

CORRESPONDENCE DATA

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NAME OF SUBMITTER: Jason Z. Lin

Total Attachments: 1

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PATENT REEL: 021754 FRAME: 0736

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ASSIGNMENT

WHEREAS, I/we, Hong Hocheng and Chin Chung Nien, whose post office address(es) appear(s) below,

	gned certain new and useful improvements in <u>IN-SITU</u> R MOLD DEFORMATION IN NANOIMPRINT			
(hereinafter referred to as the Invention) for which an application for United States Letters Patent was				
executed on even date herewith;				
 executed on; filed on, Serial No 				
☐ filed as PCT International Application No	on,designating			
The United States of America;	T 21 2005			
☑ Patent number 6,909,998 , issue on	June 21, 2005 .			
WHEREAS, National Tsing Hua University, wh	ose post office address is 101, Section 2, Kuang-Fu Road,			
Hsinchu, Taiwan 30013, R.O.C. hereinafter referred to as	ASSIGNEE, is desirous of acquiring the entire right, title and interest in			
and to the same in the United States;				
NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNORs, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.				
ALSO, ASSIGNORs hereby agree to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the Unites States for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. ASSIGNORs also agree, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the invention that are within ASSIGNORs' possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNORs in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNORs' obligations under this instrument shall extend to ASSIGNORs' heirs, executors, administrators and other legal representatives.				
ALSO, ASSIGNORs hereby authorize and request the Director of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNORs had this assignment and sale not been made.				
Assignor Name	Address			
Hong Hocheng	No. 101, Sec. 2, Guanfu Rd., Hsinchu City 300,			
Signature / /	Taiwan			
Where Signed	Date			
Taiwan, R. O. C.	10/23,2008			
Assignor Name	Address			
Chin Chung Nien	No. 195, Sec. 4, Jhongsing Rd., Jhudong Township,			
Signature Ching Man	Hsinchu County 310, Taiwan			
Where Signed Taiwan, R. O. C.	Date Oct. 21, 208			

RECORDED: 10/30/2008

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